

To: _____**Change Notification: Photocoupler and Photorelay**

We appreciate your continuous patronage of our semiconductor products.
Change is planned for the following product. Please refer to the following contents.
We would appreciate your understanding.

1. Affected product : The following product (including (TST) products).

Type	Product
PHOTO-TRIAC	TLP265J, TLP266J, TLP267J, TLP268J
PHOTORELAY	TLP175A
PHOTOVOLTAIC	TLP3905, TLP3906

2. Description of change : The following is changed.

No.	Change	Before	After	Applicable product
1)	Photo side: Shape of inner frame	See attached sheet.		All the applicable products
2)	Photo side: Wire bonding position at bonding post			TLP266J, TLP267J, TLP268J
3)	LED side: Bonding method	Normal	Low loop	TLP265J, TLP266J, TLP175A

3. Purpose of change

No.	Change	Purpose
1)	Photo side: Shape of inner frame	Unification
2)	Photo side: Wire bonding position at bonding post	Unification
3)	LED side: Bonding method	Unification

4. Product characteristics

- 1) Since the change is the shape of inner frame, there is no change in the product structure, parts and materials. Initial characteristics and reliability level will not change.

5. Schedule of change

- All the applicable products are planned to be changed from the production of October 2017.

6. Request

- Please inform us if you have any inconvenience on this change through our sales representatives by September 15, 2017.

If there is no response by the date, we will assume that you have agreed to this change.

Sincerely yours,



F. Hirano / Manager
Quality Planning Group
Quality Assurance Department
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(Drafted by T. Uchino)